

MOSFET - Power, Single P-Channel, SOT-23 -50 V, 10 Ω

BSS84L, BVSS84L, SBSS84L

- SOT-23 Surface Mount Package Saves Board Space
- BV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
|--|-------------------|--------------|---------------------------|
| Drain-to-Source Voltage | V_{DS} | -50 | Vdc |
| Gate-to-Source Voltage - Continuous | V_{GS} | ± 20 | Vdc |
| Drain Current Continuous @ $T_A = 25^\circ\text{C}$ Pulsed Drain Current ($t_p \leq 10 \mu\text{s}$) | I_D I_{DM} | -130 -520 | mA |
| Total Power Dissipation @ $T_A = 25^\circ\text{C}$ | P_D | 225 | mW |
| Operating and Storage Temperature Range | T_J, T_{stg} | -55 to 150 | $^\circ\text{C}$ |
| Thermal Resistance - Junction-to-Ambient | $R_{\theta JA}$ | 556 | $^\circ\text{C}/\text{W}$ |
| Thermal Resistance - Junction-to-Ambient (Note 1) | $R_{\theta JA}$ | 377.2 | $^\circ\text{C}/\text{W}$ |
| Maximum Lead Temperature for Soldering Purposes, for 10 seconds | T_L | 260 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

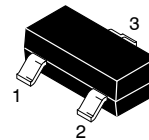
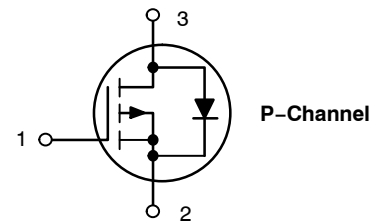
1. $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. And the $R_{\theta JA}$ is determined by the user's board design. The maximum rating presented here is based on mounting the part on JEDEC Standard 51-3/51-7.



ON Semiconductor®

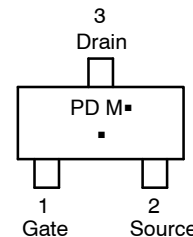
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| $V_{(BR)DSS}$ | $R_{DS(ON)} \text{ MAX}$ |
|---------------|--------------------------|
| -50 V | 10 Ω @ -10 V |



SOT-23
CASE 318
STYLE 21

MARKING DIAGRAM & PIN ASSIGNMENT



PD = Specific Device Code
M = Date Code
▪ = Pb-Free Package

(*Note: Microdot may be in either location)

ORDERING INFORMATION

| Device | Package | Shipping† |
|---|---------------------|---------------------|
| BSS84LT1G, BVSS84LT1G, SBSS84LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| BSS84LT7G | SOT-23 (Pb-Free) | 3,500 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BSS84L, BVSS84L, SBSS84L

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|--|---------------|-----|-----|--------------------|-----------------|
| OFF CHARACTERISTICS | | | | | |
| Drain-to-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = -250\ \mu\text{Adc}$) | $V_{(BR)DSS}$ | -50 | - | - | Vdc |
| Zero Gate Voltage Drain Current ($V_{DS} = -25\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) ($V_{DS} = -50\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) ($V_{DS} = -50\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$, $T_J = 125^\circ\text{C}$) | I_{DSS} | - | - | -0.1 -15 -60 | μAdc |
| Gate-Body Leakage Current ($V_{GS} = \pm 20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$) | I_{GSS} | - | - | ± 10 | nAdc |

ON CHARACTERISTICS (Note 2)

| | | | | | |
|--|--------------|------|-----|------|----------|
| Gate-Source Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = -250\ \mu\text{A}$) | $V_{GS(th)}$ | -0.9 | - | -2.0 | Vdc |
| Static Drain-to-Source On-Resistance ($V_{GS} = -5.0\text{ Vdc}$, $I_D = -100\ \text{mAdc}$) | $R_{DS(on)}$ | - | 4.7 | 10 | Ω |
| Transfer Admittance ($V_{DS} = -25\text{ Vdc}$, $I_D = -100\ \text{mAdc}$, $f = 1.0\text{ kHz}$) | $ Y_{fs} $ | 50 | - | - | mS |

DYNAMIC CHARACTERISTICS

| | | | | | | |
|----------------------|---------------------------|-----------|---|-----|---|----|
| Input Capacitance | $V_{DS} = 5.0\text{ Vdc}$ | C_{iss} | - | 36 | - | pF |
| Output Capacitance | $V_{DS} = 5.0\text{ Vdc}$ | C_{oss} | - | 17 | - | |
| Transfer Capacitance | $V_{DG} = 5.0\text{ Vdc}$ | C_{rss} | - | 6.5 | - | |

SWITCHING CHARACTERISTICS (Note 3)

| | | | | | | |
|---------------------|--|--------------|---|-----|---|----|
| Turn-On Delay Time | $V_{DD} = -15\text{ Vdc}$, $I_D = -2.5\text{ Adc}$, $R_L = 50\ \Omega$ | $t_{d(on)}$ | - | 3.6 | - | ns |
| Rise Time | | t_r | - | 9.7 | - | |
| Turn-Off Delay Time | | $t_{d(off)}$ | - | 12 | - | |
| Fall Time | | t_f | - | 1.7 | - | |
| Gate Charge | $V_{DD} = -40\text{ Vdc}$, $I_D = -0.5\text{ A}$, $V_{GS} = -10\text{ V}$ | Q_T | - | 2.2 | - | nC |

SOURCE-DRAIN DIODE CHARACTERISTICS

| | | | | | | |
|--------------------------|--|----------|---|---|--------|---|
| Continuous Current | | I_S | - | - | -0.130 | A |
| Pulsed Current | | I_{SM} | - | - | -0.520 | |
| Forward Voltage (Note 3) | $V_{GS} = 0\text{ V}$, $I_S = -130\text{ mA}$ | V_{SD} | - | - | -2.2 | V |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.
3. Switching characteristics are independent of operating junction temperature.

TYPICAL ELECTRICAL CHARACTERISTICS

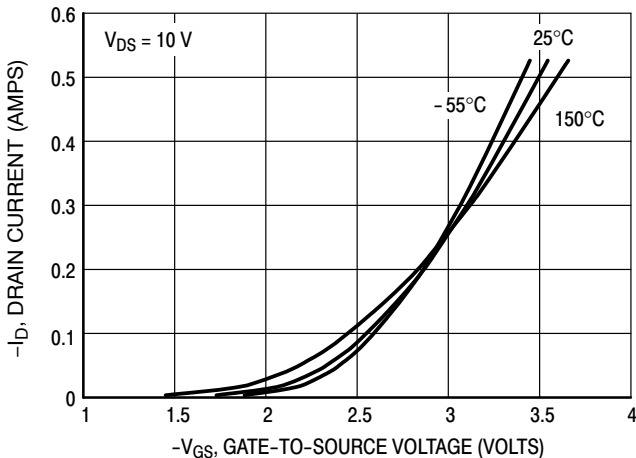


Figure 1. Transfer Characteristics

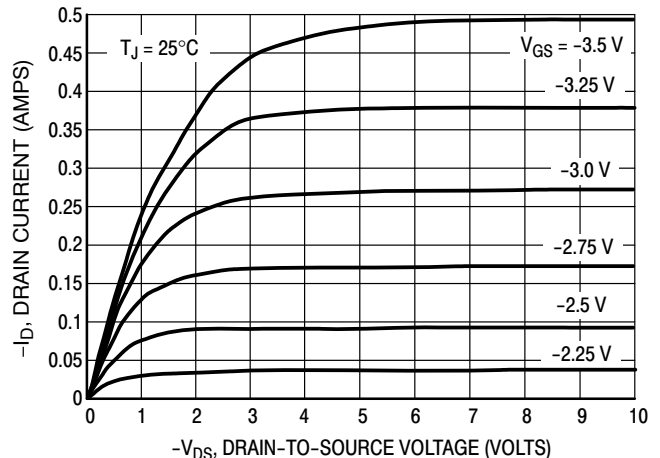


Figure 2. On-Region Characteristics

BSS84L, BVSS84L, SBSS84L

TYPICAL ELECTRICAL CHARACTERISTICS

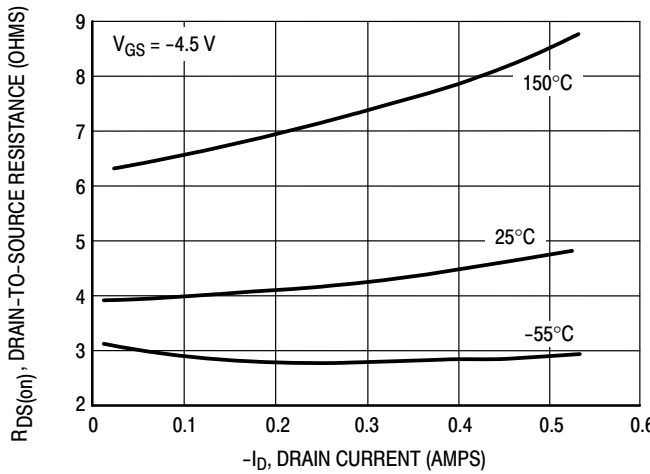


Figure 3. On-Resistance versus Drain Current

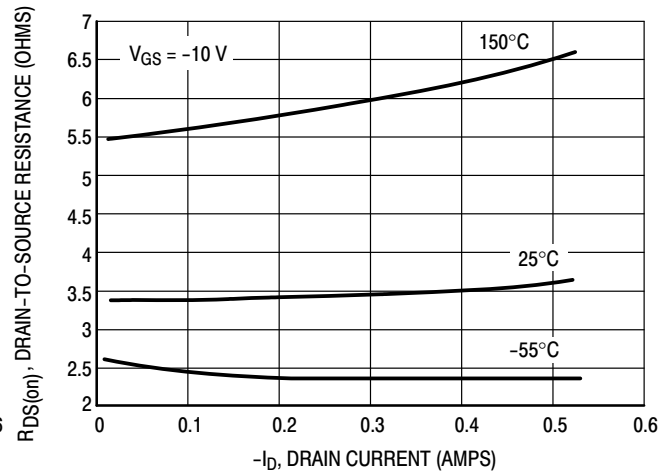


Figure 4. On-Resistance versus Drain Current

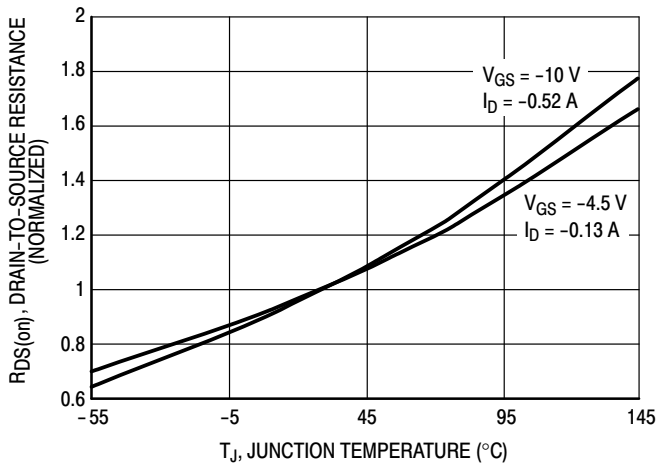


Figure 5. On-Resistance Variation with Temperature

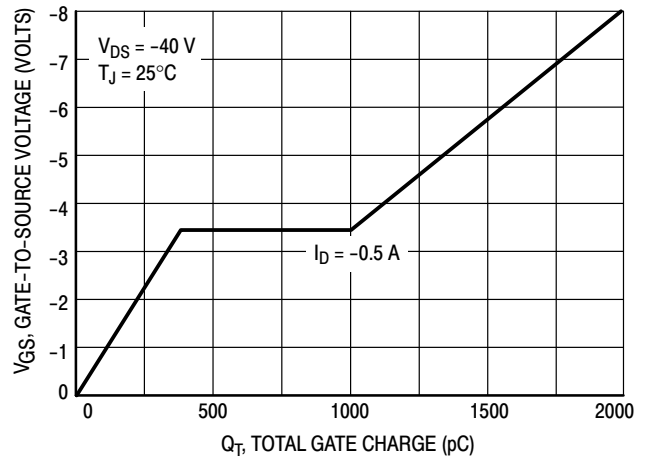


Figure 6. Gate Charge

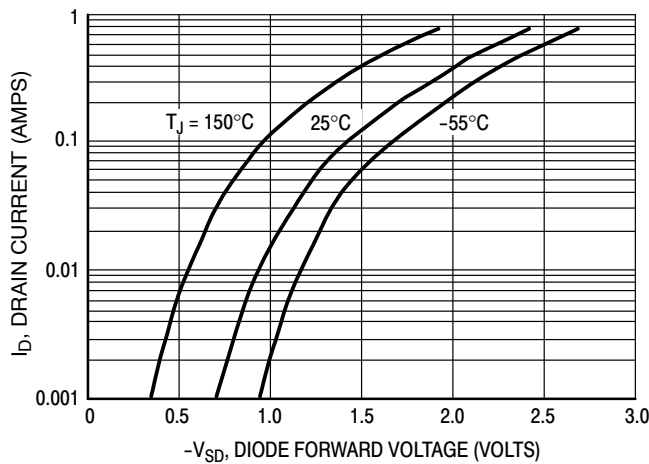


Figure 7. Body Diode Forward Voltage

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SOT-23 (TO-236)
CASE 318
ISSUE AT

DATE 01 MAR 2023

SCALE 4:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | | INCHES | | |
|----------------|-------------|------|------|--------|-------|-------|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.89 | 1.00 | 1.11 | 0.035 | 0.039 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.000 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.017 | 0.020 |
| c | 0.08 | 0.14 | 0.20 | 0.003 | 0.006 | 0.008 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.080 |
| L | 0.30 | 0.43 | 0.55 | 0.012 | 0.017 | 0.022 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.027 |
| H _E | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| T | 0° | --- | 10° | 0° | --- | 10° |

GENERIC MARKING DIAGRAM*



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



SOT-23 (TO-236) CASE 318 ISSUE AT

DATE 01 MAR 2023

| | | | | | |
|---|---|---|---|---|---|
| STYLE 1 THRU 5: CANCELLED | STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR | STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR | STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE | | |
| STYLE 9: PIN 1. ANODE 2. ANODE 3. CATHODE | STYLE 10: PIN 1. DRAIN 2. SOURCE 3. GATE | STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE | STYLE 12: PIN 1. CATHODE 2. CATHODE 3. ANODE | STYLE 13: PIN 1. SOURCE 2. DRAIN 3. GATE | STYLE 14: PIN 1. CATHODE 2. GATE 3. ANODE |
| STYLE 15: PIN 1. GATE 2. CATHODE 3. ANODE | STYLE 16: PIN 1. ANODE 2. CATHODE 3. CATHODE | STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE | STYLE 18: PIN 1. NO CONNECTION 2. CATHODE 3. ANODE | STYLE 19: PIN 1. CATHODE 2. ANODE 3. CATHODE-ANODE | STYLE 20: PIN 1. CATHODE 2. ANODE 3. GATE |
| STYLE 21: PIN 1. GATE 2. SOURCE 3. DRAIN | STYLE 22: PIN 1. RETURN 2. OUTPUT 3. INPUT | STYLE 23: PIN 1. ANODE 2. ANODE 3. CATHODE | STYLE 24: PIN 1. GATE 2. DRAIN 3. SOURCE | STYLE 25: PIN 1. ANODE 2. CATHODE 3. GATE | STYLE 26: PIN 1. CATHODE 2. ANODE 3. NO CONNECTION |
| STYLE 27: PIN 1. CATHODE 2. CATHODE 3. CATHODE | STYLE 28: PIN 1. ANODE 2. ANODE 3. ANODE | | | | |

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